



Chemtronics® — the Leader in Desoldering Technology

Soder-Wick® and Chem-Wik® Desoldering Braid

Chemtronics offers two of the top brands of desoldering braid in the industry to meet your every requirement. Soder-Wick®, the world's leading brand of desoldering braid, is the fastest, cleanest and safest braid in the industry. It significantly reduces rework/repair time and minimizes the risk of heat damage to the board. Its geometrically precise weave design allows for maximum capillary action and solder capacity. Soder-Wick® and Chem-Wik® Desoldering Braid optimize heat transfer through the braid and into the solder joint, resulting in faster wicking action than any other competitive brand. Minimal flux residue on the board speeds up the cleaning process, or eliminates it entirely.

Soder-Wick® and Chem-Wik® Desoldering Braid

Available in the most comprehensive variety of widths, lengths and flux types. Application-specific sizes allow for precise solder removal in a flash. Vacuum packaging completely protects the copper desoldering braid from the harmful effects of the environment, reducing oxidation and increasing shelf life. Soder-Wick® is available in the VacuPak™ vacuum-sealed can, which serves as a protective storage container once the pack has been opened and is easily stacked on the shelf. Its superior packaging provides predictable quality and performance, time and time again.

Soder-Wick® and Chem-Wik® Desoldering Braid Quality

Desoldering braid meets or exceeds the greatest range of qualitative and performance standards:



- MIL-F-14256 F type R flux
- NASA-STD-8739.3 Soldered Electrical Connections
- DOD-STD-883E, Method 2022
- ANSI/IPC J STD-004, Type ROL0

Static Dissipative Packaging

- Qualifies under MIL-STD-1686C and MIL-HDBK-263B as a non-ESD generator
- Meets the Static Decay Rate Provision of MIL-B-81705C and MIL-STD-2000A



Product Selection Guide

| Product | Size | Color | 5' 1.5m | 10' 3.0m | 25' 7.5m | 100' 30.5m | 500' 152.5m | VacuPak™ | Application |
|-----------------------------|---|-------------|-------------|-------------|-------------|---------------|----------------|----------|---------------------|
| Soder-Wick® BGA No Clean | BGA | Purple | 60-BGA-5 | | | | | SW160BGA | BGA Pads and Chips |
| Soder-Wick® Rosin | 1 | .030"/0.8mm | White | | 50-1-25 | | | | SMD, Micro-Circuits |
| | 2 | .060"/1.5mm | Yellow | | 50-2-25 | 50-2-100 | 50-2-500 | | Small Pads, SMDs |
| | 3 | .080"/2.0mm | Green | | 50-3-25 | 50-3-100 | 50-3-500 | | Medium Pads |
| | 4 | .110"/2.8mm | Blue | | 50-4-25 | 50-4-100 | 50-4-500 | | Large Pads |
| | 5 | .145"/3.7mm | Brown | | 50-5-25 | | | | Terminals |
| | 6 | .210"/5.3mm | Red | | 50-6-25 | | | | Large Lugs |
| Soder-Wick® Rosin SD |  | 1 | .030"/0.8mm | White | 80-1-5 | 80-1-10 | | SW18015 | SMD, Micro-Circuits |
| | | 2 | .060"/1.5mm | Yellow | 80-2-5 | 80-2-10 | | SW18025 | Small Pads, SMDs |
| | | 3 | .080"/2.0mm | Green | 80-3-5 | 80-3-10 | | SW18035 | Medium Pads |
| | | 4 | .110"/2.8mm | Blue | 80-4-5 | 80-4-10 | | SW18045 | Large Pads |
| | | 5 | .145"/3.7mm | Brown | 80-5-5 | 80-5-10 | | SW18055 | Terminals |
| | | 6 | .210"/5.3mm | Red | 80-6-5 | | | | |
| Soder-Wick® No Clean SD |  | 1 | .030"/0.8mm | White | 60-1-5 | 60-1-10 | | SW16015 | SMD, Micro-Circuits |
| | | 2 | .060"/1.5mm | Yellow | 60-2-5 | 60-2-10 | | SW16025 | Small Pads, SMDs |
| | | 3 | .080"/2.0mm | Green | 60-3-5 | 60-3-10 | | SW16035 | Medium Pads |
| | | 4 | .110"/2.8mm | Blue | 60-4-5 | 60-4-10 | | SW16045 | Large Pads |
| | | 5 | .145"/3.7mm | Brown | 60-5-5 | 60-5-10 | | SW16055 | Terminals |
| | | 6 | .210"/5.3mm | Red | 60-6-5 | | | | |
| Soder-Wick® Unfluxed |  | 2 | .060"/1.5mm | Yellow | | 70-2-25 | | | Small Pads, SMDs |
| | | 3 | .080"/2.0mm | Green | | 70-3-25 | | | Medium Pads |
| Soder-Wick® Unfluxed SD |  | 2 | .060"/1.5mm | Yellow | | 75-2-10 | | | Small Pads, SMDs |
| | | 3 | .080"/2.0mm | Green | | 75-3-10 | | | Medium Pads |
| | | 4 | .110"/2.8mm | Blue | | 75-4-10 | | | Large Pads |
| Soder-Wick® Lead-Free SD |  | 1 | .030"/0.8mm | White | 40-1-5 | | | | SMD, Micro-Circuits |
| | | 2 | .060"/1.5mm | Yellow | 40-2-5 | 40-2-10 | | SW14025 | Small Pads, SMDs |
| | | 3 | .080"/2.0mm | Green | 40-3-5 | 40-3-10 | | SW14035 | Medium Pads |
| | | 4 | .110"/2.8mm | Blue | 40-4-5 | 40-4-10 | | SW14045 | Large Pads |
| Soder-Wick® Silk |  | 1 | .030"/0.8mm | White | 20-1-5 | | | SW12015 | SMD, Micro-Circuits |
| | | 2 | .060"/1.5mm | Yellow | 20-2-5 | | | SW12025 | Small Pads, SMDs |
| | | 3 | .080"/2.0mm | Green | 20-3-5 | | | SW12035 | Medium Pads |
| | | 4 | .110"/2.8mm | Blue | 20-4-5 | | | SW12045 | Large Pads |
| | | 5 | .145"/3.7mm | Brown | 20-5-5 | | | SW12055 | Terminals |
| | | 6 | .210"/5.3mm | Red | 20-6-5 | | | SW12065 | Large Lugs |

ASK THE EXPERTS!

Chemtronics has application specialists standing by to identify the best solution for you. Call 800-645-5244 or e-mail askchemtronics@chemtronics.com.





Available in static dissipative (SD) packaging:



- Reduces the risk of damage associated with static electricity
- Meets MIL-STD-883B, Bellcore TR-NWT-000078, ANSI/IPC J SF-818

SII SODER-WICK®
Desoldering Braid



VacuPak™ Vacuum Sealed Packaging

Guarantees Soder-Wick Desoldering Braid to be as fast and fresh as the day it was made. The VacuPak can contains 10 bobbins with 5 feet of braid on each bobbin.

All other wick in PermaPak™ barrier packaging, 25 bobbins per package.

Soder-Wick® BGA

Most effective, economical way to safely and completely remove solder from BGA pads and chips

- Sized and designed specifically for BGA pad and chip rework/repair
- Entire BGA pads cleaned in three to four passes
- Available in rosin and no-clean fluxes
- Packaged in ESD-safe static dissipative bobbins

Soder-Wick® Rosin

Fastest, safest rosin flux desoldering braid for removing solder from printed circuit boards

- Noncorrosive ultra high purity Type R rosin flux
- Minimizes the risk of heat damage to the board
- Will not leave ionic contamination on the boards

Soder-Wick® No Clean

Fastest, cleanest no-clean flux desoldering braid packaged in static dissipative bobbins

- Patented noncorrosive, halide free, organic no-clean flux
- Desolders up to 40% faster than competitive no-clean braids and leaves boards cleaner
- Meets MIL-STD-883B, Bellcore TR-NWT-000078 and ANSI IPC SF-818 for Surface Insulation Resistance
- Meets parameters tested by the Singapore Institute of Standards and Industrial Research (SISR) for Solderability
- ANSI/IPC J STD-004, Type ROL0

Soder-Wick® Unfluxed

Unfluxed desoldering braid which can be coated with any flux type

- Can be coated with any flux type
- Allows for a consistent flux type throughout the production process
- Provides quick and safe desoldering

Soder-Wick® Lead-Free

Fastest, safest desoldering braid formulated specifically for use with lead-free applications

- Engineered specifically for high temperature, lead-free solders
- Transfers heat to the solder joint more quickly and efficiently than conventional desoldering braids
- Specifically designed for all lead-free solders
- Can also be used with Tin/Lead solders
- Noncorrosive ultra high purity no-clean flux
- Will not leave ionic contamination on the boards
- Especially effective at removing residual solder from SMT pads
- Patent pending

Soder-Wick® Silk

Engineered for desoldering without risking scratched pads and resist

- Smoother weave that reduces scratching damage
- No Clean, lead-free flux removes all solders
- Especially effective for solder removal for SMT devices



Chem-Wik® Desoldering Braid

As the standard desoldering braid for service and repair, Chem-Wik® Desoldering Braid ensures fast and safe desoldering. The ultra-pure, oxygen free copper braid quickly and completely removes solder from circuit boards and components. Its fast wicking action protects components from harmful heat damage. PermaPak™ Barrier Packaging ensures ultimate braid freshness and speed by sealing out harmful effects of the environment and protecting against oxidation.

Chem-Wik® Desoldering Braid

Meets or exceeds the greatest range of performance standards:

- MIL-F-14256F Type R
- NASA STD-8739.3 Soldered Electrical Connections
- ANSI/IPC J STD-004, Type ROL0



PermaPak™ Barrier Packaging contains 25 bobbins per package



Chem-Wik® Rosin

The fast, safe rosin flux desoldering braid for removing solder from leads and components

- Coated with ultra high purity rosin
- Quickly and thoroughly removes solder
- Noncorrosive Type R rosin flux

Available in static dissipative (SD) packaging:

- Chem-Wik® Rosin packaged in static dissipative bobbins
- Reduces the risk of damage associated with static electricity
- DOD Standard 1686C and MIL-HDBK-263B
- Mil-Std-2000A
- Mil-B-81705C Static Decay Rate Provision

Product Selection Guide

| Product | Color | Size | Length | | | | Application | |
|--------------------|--------|-------------|------------|-------------|--------------|---------------|-------------|----------------|
| | | | 5' 1.5m | 25' 7.5m | 50' 15.0m | 100' 30.5m | | 500' 152.5m |
| Chem-Wik® Rosin | Gray | .030"/0.8mm | | 2-25L | 2-50L | 2-100L | 2-500L | Micro-Circuits |
| | Yellow | .050"/1.3mm | | 5-25L | 5-50L | 5-100L | 5-500L | Small Pads |
| | Green | .075"/1.9mm | | 7-25L | 7-50L | 7-100L | 7-500L | Medium Pads |
| | Blue | .100"/2.5mm | | 10-25L | 10-50L | 10-100L | 10-500L | Large Pads |
| Chem-Wik® Rosin SD | Gray | .030"/0.8mm | 2-5L | | | | | Micro-Circuits |
| | Yellow | .050"/1.3mm | 5-5L | | | | | Small Pads |
| | Green | .075"/1.9mm | 7-5L | | | | | Medium Pads |
| | Blue | .100"/2.5mm | 10-5L | | | | | Large Pads |



ASK THE EXPERTS!

Chemtronics has application specialists standing by to identify the best solution for you. Call 800-645-5244 or e-mail askchemtronics@chemtronics.com.

